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In re Application of: Steve M. Danziger, et al.

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Art Unit: TO BE ASSIGNED

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For: Method and Apparatus for Evaluating a Known Good Die Using
Both Wire Bond and Flip-Chip Interconnects



APPLICATION DATA SHEET

(1) APPLICANT INFORMATION

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(3) APPLICANT INFORMATION

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Known Good Die Using Both Wire Bond and
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Type of Application Utility

This case is a Divisional of USPTO Serial
Number 09/321,565, filed May 28, 1999 and
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(4) REPRESENTATIVE INFORMATION

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(5) DOMESTIC PRIORITY INFORMATION

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Number 09/321,565, filed May 28, 1999 and
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(6) FOREIGN PRIORITY INFORMATION

None

(7) ASSIGNEE INFORMATION

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